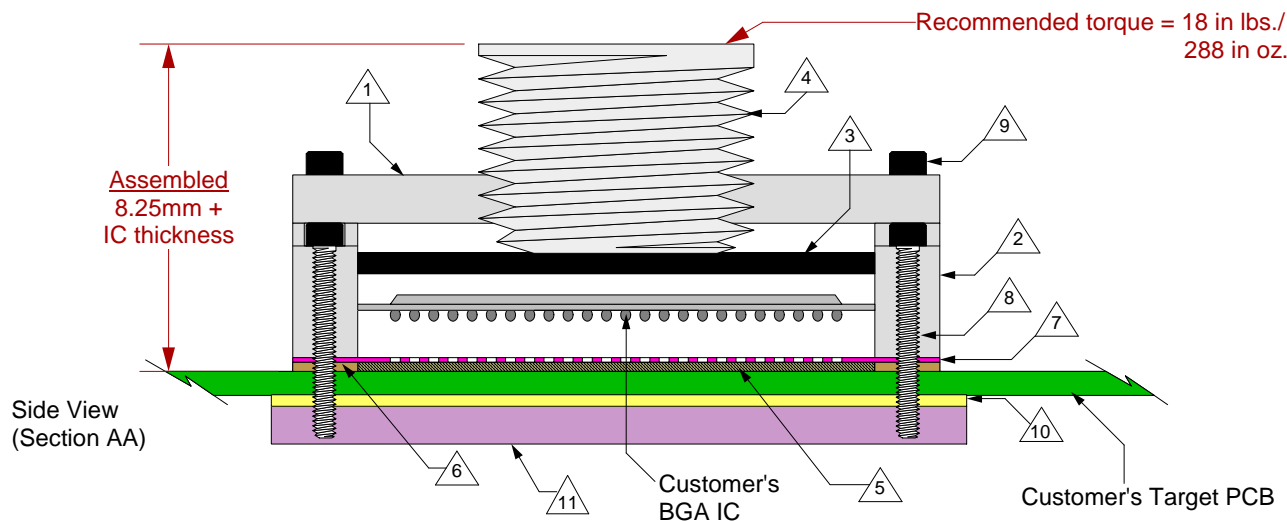
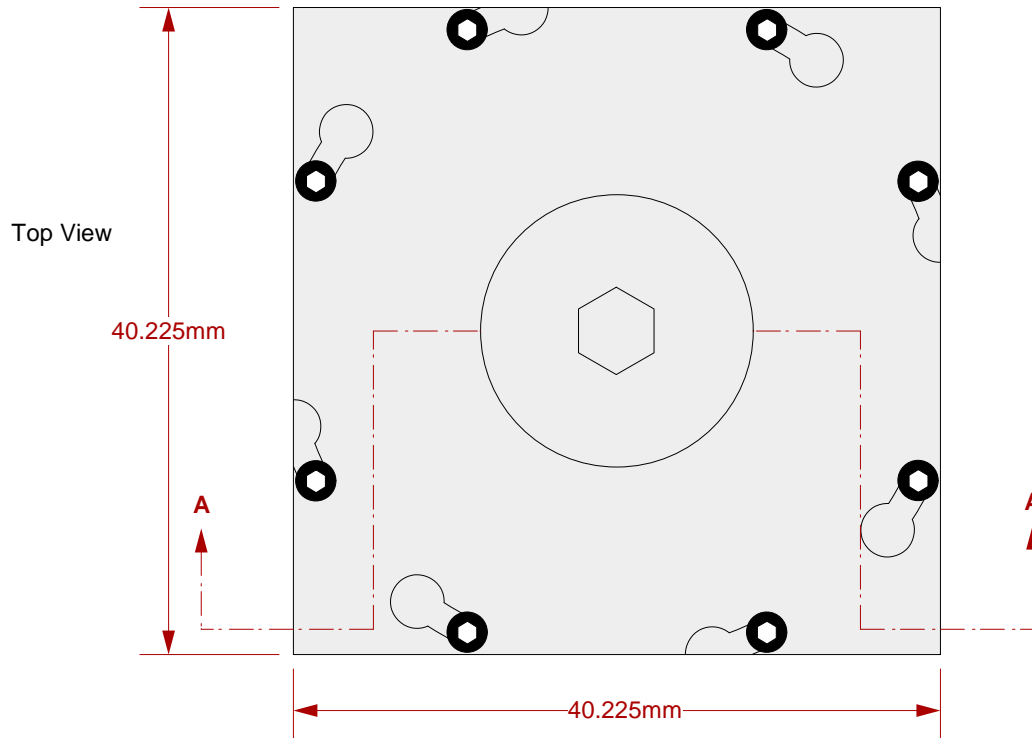


# GHz BGA Socket - Direct mount, solderless

## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



- 1 Socket Lid: Black anodized Aluminum.  
Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum.  
Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum.  
Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum.  
Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass  
filaments arranged symmetrically in a silicone  
rubber (63.5 degree angle).  
Thickness = 0.75mm.
- 6 Elastomer Guide: Cirlex or equivalent  
Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, Alloy steel with  
black oxide finish, 0-80 fine thread, 12.7mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine  
thread.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Backing Plate: Black anodized Aluminum.  
Thickness = 6.35mm.

## SG-BGA-6014 Drawing

Status: Released

Scale: -

Rev: G

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337  
Tele: (952) 229-8200  
www.ironwoodelectronics.com

Drawing: Meghann Fedde

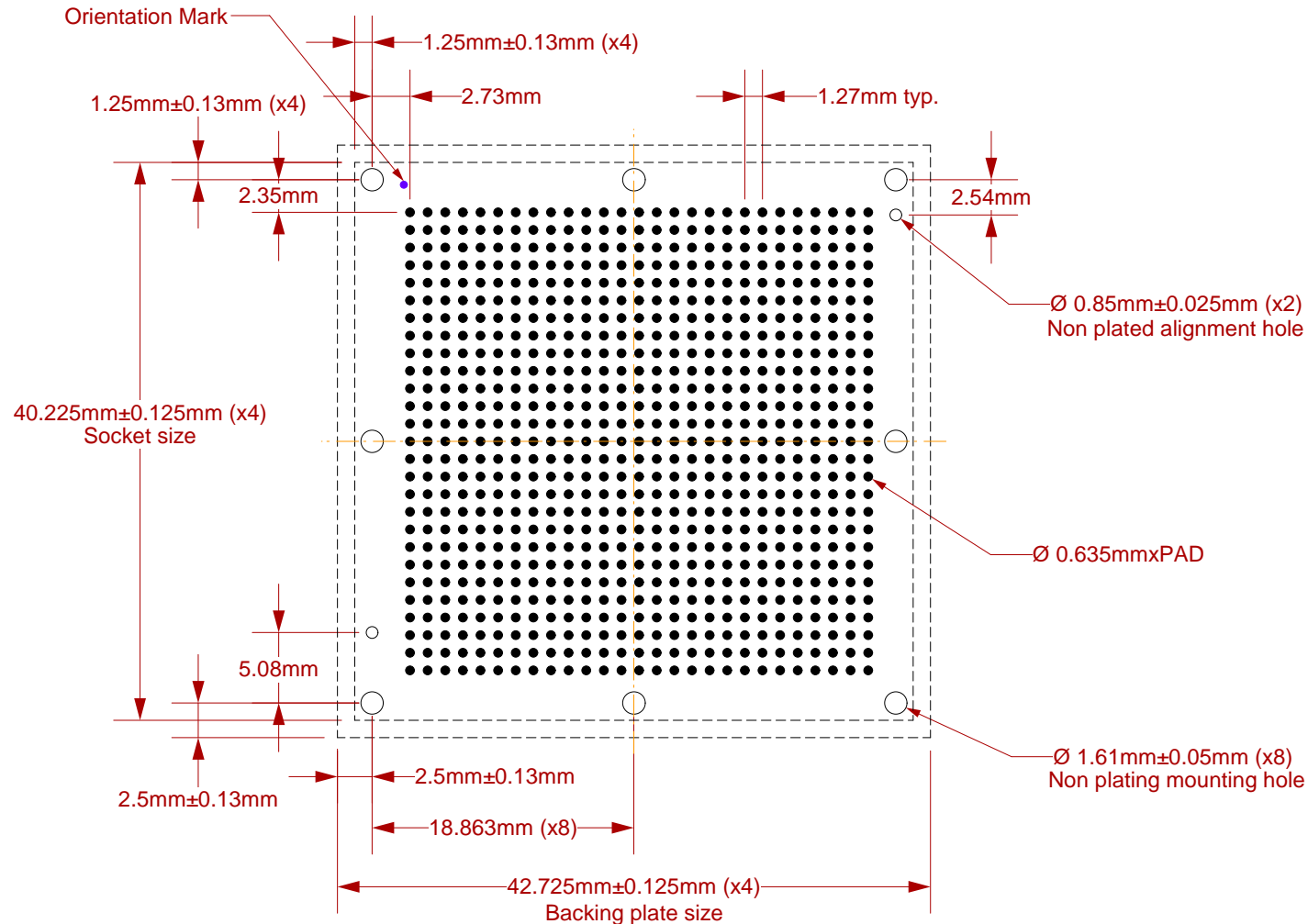
Date: 8/20/01

File: SG-BGA-6014 Dwg

Modified: 6/15/09, AE

All tolerances:  $\pm 0.125\text{mm}$  (unless stated otherwise). Materials and specifications are subject to change without notice.

**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**



**Target PCB Recommendations**


Total thickness: 2.4mm min.

Plating: Gold or Solder finish

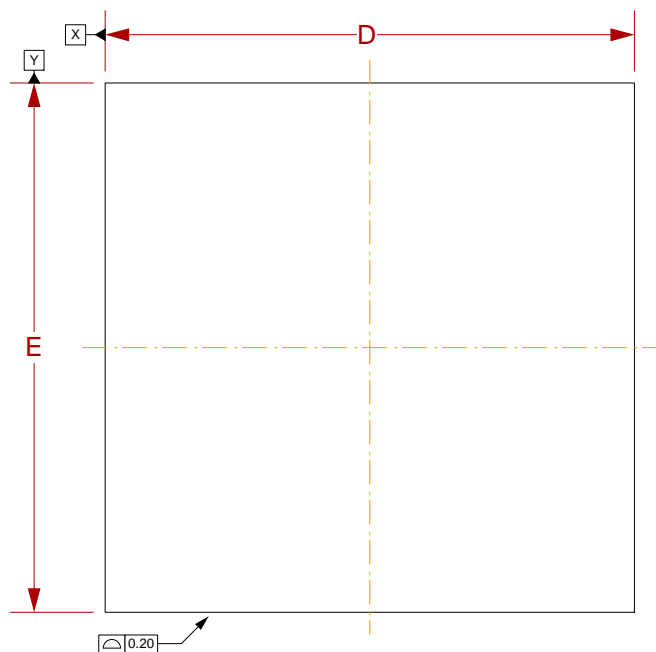
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

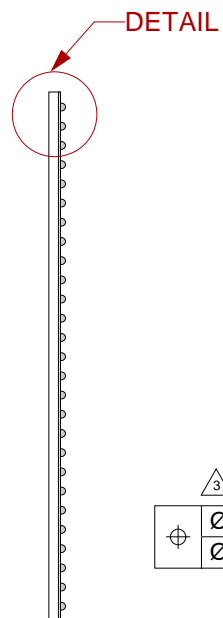
Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.

<b>SG-BGA-6014 Drawing</b>		Status: Released	Scale: 2:1	Rev: G
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: Meghann Fedde		Date: 8/20/01	
	File: SG-BGA-6014 Dwg		Modified: 6/15/09, AE	

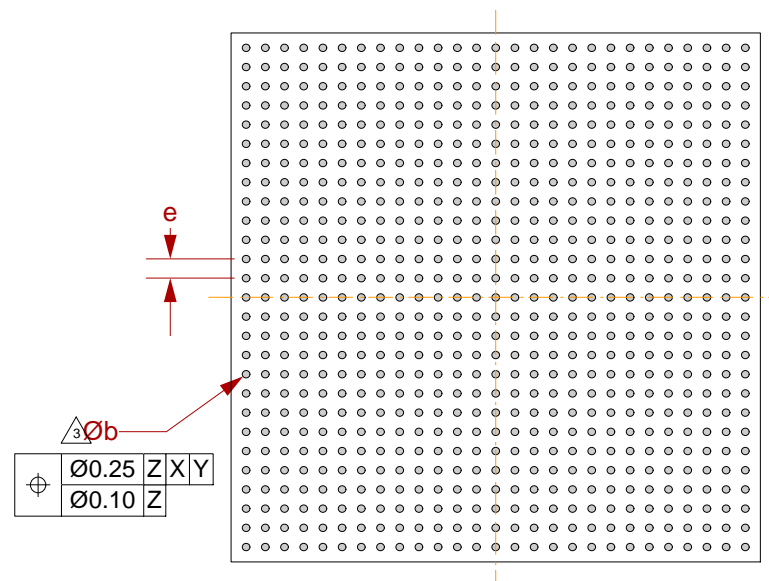
# Compatible BGA Spec



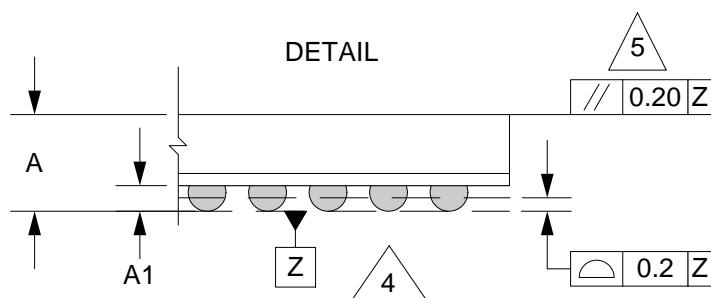
TOP VIEW



SIDE VIEW




BOTTOM VIEW



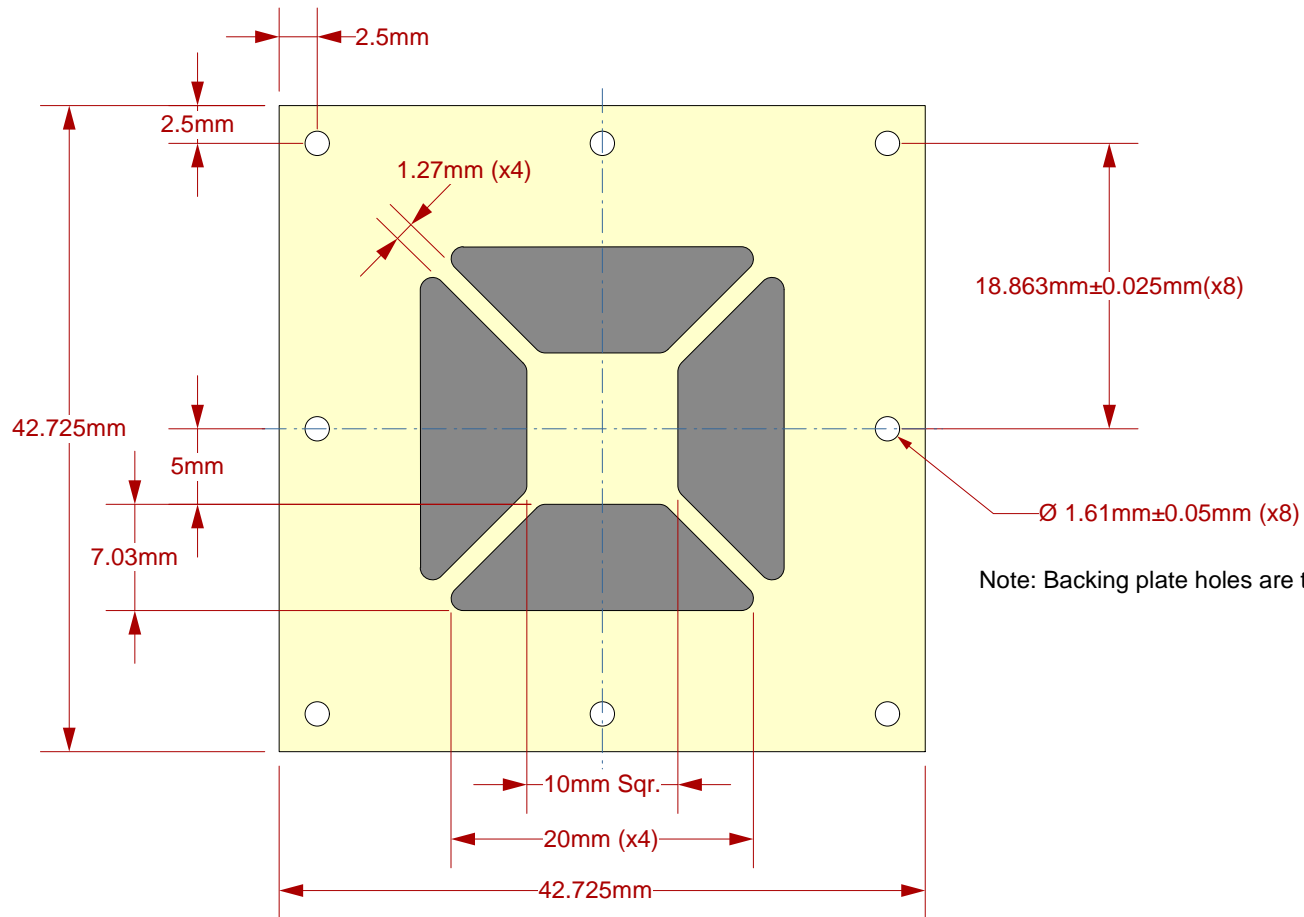
- △1 Dimensions are in millimeters.
- △2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- △4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- △5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.5	0.7
b		0.90
D	35.0 BSC	
E	35.0 BSC	
e	1.27 BSC	

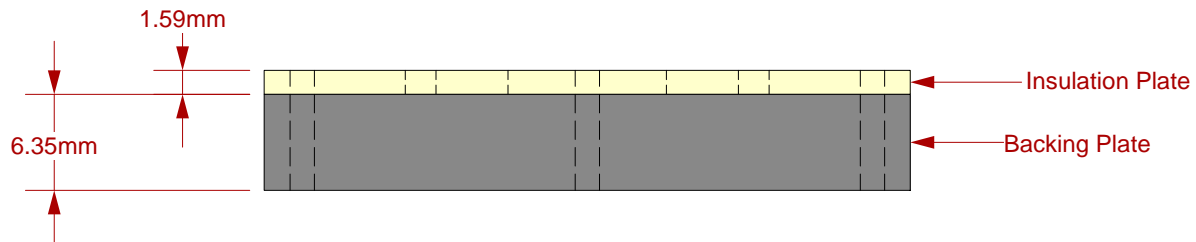
Array 27x27

	<b>SG-BGA-6014 Drawing</b>		Status: Released	Scale: -	Rev: G
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			File: SG-BGA-6014 Dwg		Modified: 6/15/09, AE

Top View




Side View



Description: Insulation Plate and Backing Plate

PAGE 4 of 4

<b>SG-BGA-6014 Drawing</b>	Status: Released	Scale: -	Rev: G
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	File: <b>SG-BGA-6014</b> Dwg		Modified: 6/15/09, AE

All dimensions are in mm.  
 All tolerances are  $\pm 0.125$ mm.  
 (Unless stated otherwise)